Preferred Devices

# **VHF/UHF Transistor**

## **NPN Silicon**

• Device Marking: 3EM

#### **Features**

• Pb–Free Package May be Available. The G–Suffix Denotes a Pb–Free Lead Finish

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	VCEO	25	Vdc
Collector-Base Voltage	VCBO	30	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	3.0	Vdc

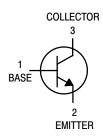
#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ heta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina



## http://onsemi.com





CASE 318 SOT-23 STYLE 6

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBTH10LT1	SOT-23	3000/Tape & Reel
MMBTH10LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBTH10-4LT1	SOT-23	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				•	•
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)</sub> CEO	25	_	-	Vdc
Collector–Base Breakdown Voltage ( $I_C = 100 \mu Adc$ , $I_E = 0$ )	V(BR)CBO	30	-	-	Vdc
Emitter–Base Breakdown Voltage ( $I_{E} = 10 \mu Adc, I_{C} = 0$ )	V(BR)EBO	3.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 25 Vdc, I <sub>E</sub> = 0)	ICBO	-	-	100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = 2.0 Vdc, I <sub>C</sub> = 0)	IEBO	-	-	100	nAdc
ON CHARACTERISTICS					
DC Current Gain (I <sub>C</sub> = 4.0 mAdc, V <sub>CE</sub> = 10 Vdc)  MMBTH10I MMBTH10-4I		60 120	_ _	- 240	_
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 4.0 mAdc, I <sub>B</sub> = 0.4 mAdc)	VCE(sat)	-	_	0.5	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 4.0 mAdc, V <sub>CE</sub> = 10 Vdc)	V <sub>BE</sub>	-	_	0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS	<u> </u>			•	
Current-Gain - Bandwidth Product (I <sub>C</sub> = 4.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 100 MHz) MMBTH10I MMBTH10-4I		650 800	_ _	- -	MHz
Collector–Base Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>cb</sub>	-	-	0.7	pF
Common–Base Feedback Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>rb</sub>	-	-	0.65	pF
Collector Base Time Constant (I <sub>C</sub> = 4.0 mAdc, V <sub>CB</sub> = 10 Vdc, f = 31.8 MHz)	rb′C <sub>C</sub>	-	-	9.0	ps

#### **TYPICAL CHARACTERISTICS**

#### **COMMON-BASE y PARAMETERS versus FREQUENCY**

 $(V_{CB} = 10 \text{ Vdc}, I_{C} = 4.0 \text{ mAdc}, T_{A} = 25^{\circ}\text{C})$ 

### yib, INPUT ADMITTANCE

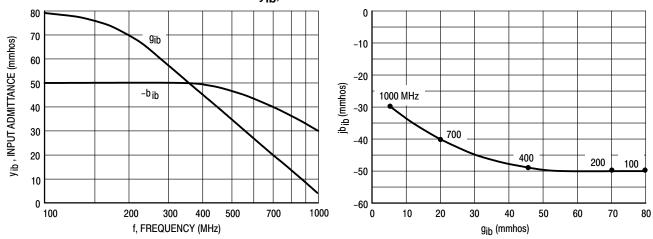


Figure 1. Rectangular Form

Figure 2. Polar Form

### yfb, FORWARD TRANSFER ADMITTANCE

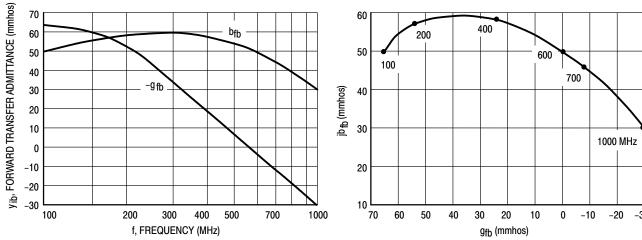


Figure 3. Rectangular Form

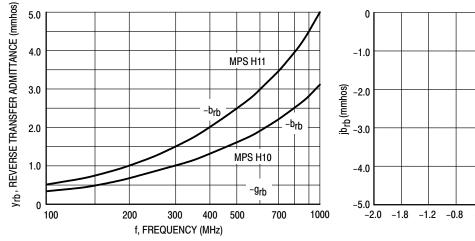
Figure 4. Polar Form

#### **TYPICAL CHARACTERISTICS**

#### **COMMON-BASE y PARAMETERS versus FREQUENCY**

 $(V_{CB} = 10 \text{ Vdc}, I_{C} = 4.0 \text{ mAdc}, T_{A} = 25^{\circ}\text{C})$ 

### yrb, REVERSE TRANSFER ADMITTANCE



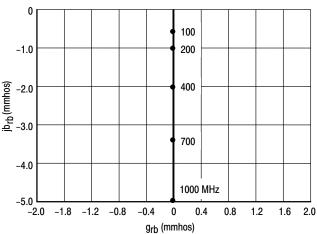
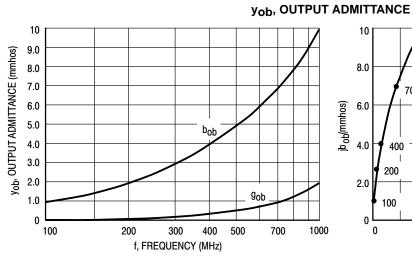


Figure 5. Rectangular Form

Figure 6. Polar Form



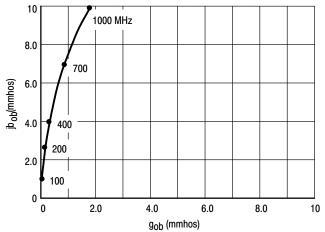
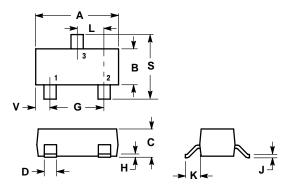


Figure 7. Rectangular Form

Figure 8. Polar Form

#### **PACKAGE DIMENSIONS**

SOT-23 (TO-236AB) CASE 318-08 **ISSUE AH** 



- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE
- MATERIAL.
  4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.1102	0.1197	2.80	3.04	
В	0.0472	0.0551	1.20	1.40	
C	0.0350	0.0440	0.89	1.11	
D	0.0150	0.0200	0.37	0.50	
G	0.0701	0.0807	1.78	2.04	
H	0.0005	0.0040	0.013	0.100	
7	0.0034	0.0070	0.085	0.177	
K	0.0140	0.0285	0.35	0.69	
L	0.0350	0.0401	0.89	1.02	
S	0.0830	0.1039	2.10	2.64	
٧	0.0177	0.0236	0.45	0.60	
STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR					

#### **SOLDERING FOOTPRINT\***

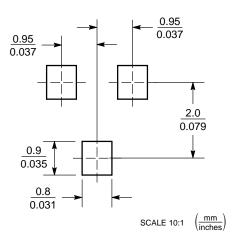


Figure 9. SOT-23

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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